ABSTRACT OF THE DISCLOSURE

There is disclosed a process for producing a resin-sealed type electronic device which comprises forming a dam frame on edge and side portions of a substrate loaded with a single or a plurality of electronic elements so as to encompass the electronic elements by sticking down a pressure sensitive adhesive sheet to the substrate, pouring a resin for sealing in the inside of the dam frame, and heat-curing the poured resin. The process dispenses with intricate production step or a long time in forming the dam frame, thus enabling to form the same with minimized number of production steps and shortest time.